

μAppS Microwave Application Seminars - Technical Program

Tuesday, June 14, 2005 - LBCC Exhibit Hall		
Session I Active Components		
la	SiGe BiCMOS Transceiver and SiGe Power Amplifier for 5.8GHz WDCT Apps Reimann, Krimmer, <i>Atmel</i>	9 - 9:20 AM
lb	A 5-6GHz High Gain SiGe Power Amplifier Bischof, Gerlach, <i>Atmel</i>	9:20 - 9:40 AM
<i>IMS Plenary Session (above Exhibit Hall)</i>		<i>9:40 - 12PM</i>
lc	Transient Protection of MMIC Amplifiers Mikhail Mordkovich, <i>Mini-Circuits</i>	12 - 12:20PM
ld	PA Plus Sean Martin, <i>Skyworks</i>	12:20 - 12:40PM
le	AlGaAs PIN Diode Switches Curcio, Boles, Brogle, Hoag, Russell, <i>M/A-Com</i>	12:40 - 12:50PM
lf	Heterolithic Microwave Integrated Circuits Timothy Boles, <i>M/A-Com</i>	12:50 - 1PM
lg	Very High Power MMICs Using 24V HVMSAG GaAs Process Ed Griffin, <i>M/A-Com</i>	1 - 1:10PM
lh	High Linearity HBT Driver Amplifiers McIntosh, Dalton, Fox, Rizzi, <i>M/A-Com</i>	1:10 - 1:20PM
li	Automotive Applications for GaAs MMIC Amplifiers Gerard Delaval / Philippe Labasse, <i>UMS</i>	1:20 - 1:40PM
Session II Components		
IIa	Dual-band Filtered GPS Low-noise Amplifier Walter E. Gordon, <i>Spectrum Microwave</i>	1:40 - 2PM
IIb	Low Phase Noise Crystal Oscillators in High Vibration Environments Davis, Painter, <i>Crane Aero & Electronics STC Microwave</i>	2 - 2:20PM
IIc	A New High Q Microwave Resonator Tech for Oscillator and Filter Apps Bates, Zaloglu, <i>Dielectric Labs</i>	2:20 - 2:30PM
IId	Miniature LTCC Passive VHF and UHF Components Setty, Gamliel, Dornhelm, <i>Mini-Circuits</i>	2:30 - 2:40PM
IIe	LTCC Mixer Amplifiers Provide S-of-A Performance Ji, Setty, <i>Mini-Circuits</i>	2:40 - 2:50PM
IIf	Embedded RFID Readers Weigand, <i>M/A-Com</i> , Reynolds, <i>ThingMagic</i>	2:50 - 3PM
IIg	New Chipscale Small-Footprint PIN Diodes Brogle, Curcio, Bukowski, <i>M/A-Com</i>	3 - 3:10PM

IIh	High Performance Multi-Throw Switches for GSM Handset Apps Samiotes, Bawell, <i>M/A-Com</i>	3:10 - 3:30PM
IIi	Optical Micro-Resonator Microwave or Optical Filters Danny Fung, <i>OEwaves</i>	3:30 - 3:50PM
IIj	Difference Between CMOS and GaAs Switch Performance Ray Baker, <i>Peregrine Semiconductor</i>	3:50 - 4:10PM
IIk	Taming the EDGE Penalty in Handset Design Daniel Schwartz, <i>Freescale</i>	4:10 - 4:30PM
III	Application Principles for Circulators and Isolators Quintanilla, Eldridge, <i>M2 Global Technology</i>	4:30 - 4:50PM
Wednesday, June 15, 2005		
Session III CAD		
IIIa	CAD and Modeling Products and Techniques Cris Emson, <i>Vector Fields</i>	9 - 9:20AM
IIIb	Mixer Synthesis using Eagleware-Elanix GENESYS Ehrich, Rhea, <i>Eagleware Corp.</i>	9:20 - 9:40AM
IIIc	IE3D EM Simulation & Optimization Package Ver. 11 Jian-X. Zheng, <i>Zeland Software</i>	9:40 - 10AM
IIId	Accurate Models Accelerate Reference Designs for RFIC Amplifiers Capwell, Clausen, Connick, Weller, Dunleavy, <i>Modelithics</i>	10 - 10:20AM
IIIe	FEKO EM Structure Simulator Madelein O'Brien, <i>EMSS</i>	10:20 - 10:40AM
IIIf	Time Gated Statistical Analysis of Power Richard Theiss, <i>Boonton Electronics</i>	10:40 - 11AM
IIIg	Innovative Methods in Remcom Inc. Simulation Software Luebbbers, Langdon, Carpenter, <i>Remcon</i>	11 - 11:20AM
IIIh	A Novel Software System for Hybrid Electromagnetic-thermodynamic Simulation Malgorzata Celuch, <i>QWED & Warsaw Univ. of Tech.</i>	11:20 - 11:40AM
IIIi	WASP-NET Fast Microwave Component and Antenna Design and Optimization Fritz Arndt, <i>MiG Microwave Innovation</i>	11:40 - 12PM
IIIj	µWaveWizard CAD Solution for Passive Waveguide Components Thomas Sieverding, <i>MICIAN</i>	12 - 12:20PM
IIIk	EMPiCASSO, EMCube and EMTerrano: CAD Tools for EM Modeling Kazem Sabet, <i>EMAG Tech</i>	12:20 - 12:40PM
IIIl	Neural Based Modeling of EM Structures and Microwave Devices Q.J. Zhang, <i>Carleton University</i>	12:40 - 1PM
IIIm	Schematic-driven EM Extraction	1 - 1:20PM

Michael Heimlich, *Applied Wave Research*

Session IV Packages & Materials

IVa	Millimeter Wave Imaging - Camera Systems David Vizard, <i>Farran Technology</i>	1:20 - 1:40PM
IVb	ELVA-1 Family of Broadband Mm-Wave Radios Korneev, Kanareykin, Berezin, <i>ELVA-1 Millimeter Wave</i>	1:40 - 2PM
IVc	Enhanced Thin Film Tech. for High Density Integration Kaegi, Feurer, <i>Reinhardt Microtech</i>	2 - 2:20PM
IVd	Conductor Surface Profile (Rrms) on Total Attenuation in Microstrip & Stripline Normyle, McCarthy, Wynants, <i>Taconic</i>	2:20 - 2:40PM
IVe	Ultra Stable Tuner Vince Mallette, <i>Focus Microwaves Inc.</i>	2:40 - 2:50PM
IVf	Universal Multi-Purpose Tuner Christos Tsironis, <i>Focus Microwaves Inc.</i>	2:50 - 3PM
IVg	High-Power, High-Speed 100MHz to 1.0GHz Programmable Tuner Roman Meierer, <i>Focus Microwaves Inc.</i>	3 - 3:10PM
IVh	High Performance Silicon Based Passive Modulators Houlihan, Ebbeson, <i>M/A-Com</i>	3:10 - 3:30PM
IVi	R-Pak High Power RF & Microwave Liquid Crystal Polymer Packages Roman, Dewire, <i>RJR Polymers</i>	3:30 - 3:50PM
IVj	Integrating Thermal Management Solutions in PWBs Johnson, McMaster, <i>Merix Corp.</i>	3:50 - 4:10PM
IVk	Organic Laminate Alternative to LTCC Jim Chamberlin, <i>JMD</i>	4:10 - 4:30PM
IVl	Microwave Digital Receiver Design Technique Yi, Yang, <i>HeFei Htmicrowave Co.,Ltd</i>	4:30 - 4:50PM

Thursday June 16, 2005

Session V Test & Measurement

Va	Millimeterwave Measurement of Complex Permittivity Suzuki, Kamijo, <i>Keycom</i>	9 - 9:20AM
Vb	Advances in Load-Pull Based Device Characterization Gary Simpson, <i>Maury Microwave</i>	9:20 - 9:40AM
Vc	Modern VNA Measurement Techniques for Mixers and Amplifiers David Savage, <i>Agilent</i>	9:40 - 10AM

Session VI Components & Processes

Vla	Electroless and Electrolytic Au Plating for RoHS Compliant Packaging Liang, <i>MCV Technologies, Inc.</i> , Dye, <i>Evantec Micro.</i>	10 - 10:20AM
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Vlb	Miniature Low Loss High Selectivity Microwave Planar Filters Bates, Zagloglu, <i>Dielectric Labs</i>	10:20 - 10:40AM
Vlc	Millimeterwave Frequency Converters 18 - 325 GHz Tingting Liu, <i>Farran Technology</i>	10:40 - 11AM
Vld	Direct Quadrature Modulator Wesley Boyd, <i>Skyworks</i>	11 - 11:20AM
Session VII Power Amplifiers + 2		
VIIa	45W/90W/180W GaN HEMT for Base Station Applications Shigeru Nakajima, <i>Eudyna Devices</i>	11:20 - 11:40AM
VIIb	200kW 352MHz Power Amplifier Using LDMOS Transistors S.K. Leong, <i>Polyfet RF Devices</i>	11:40 - 12PM
VIIc	1kW, 'L' Band, CW Solid State Amplifier for Pulsed Radar Immunity Testing Dominic FitzPatrick, <i>Milmega</i>	12 - 12:20PM
VIIId	Linear SiGe Amplifiers for WLAN/PHS Applications Dalton, Fox, <i>M/A-Com</i>	12:20 - 12:40PM
VIIe	Power Amplifiers for Cordless Telephone Applications Zhao, Studtmann, <i>M/A-Com</i>	12:40 - 1PM
VIIIf	Multi-Frequency 24 - 100 GHz Transceiver Chip Tim Childs, <i>TLC Precision Wafer Tech.</i>	1 - 1:20PM
VIIg	Air Cavity LCP (Liquid Crystal Polymer) Packaging Michael Zimmerman, <i>Quantum Leap Packaging</i>	1:20 - 1:40PM